

UN-PACKAGED OR SEMI-PACKAGED ELECTRICALLY TESTED
ELECTRONIC DEVICE FREE FROM INFANTILE MORTALITY AND
PROCESS FOR MANUFACTURE THEREOF

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ABSTRACT

An un-packaged or semi-packaged, electrically tested electronic device, free from infantile mortality, characterized in that it comprises a silicon platelet or die (11) having a top surface and a bottom surface, in which an integrated circuit is realized externally accessible through a plurality of connection pads and an array of connection pins (10; 13; 14) which are mechanically and removably connected to said silicon die (11) by connection means and are electrically connected to the connection pads of said silicon die (11) by electric connection means (12).